

# Plaskon ALP-2 (197)

Epoxy; Epoxide

Cookson Electronics - Semiconductor Products

## Message:

This material is an epoxy encapsulant for high productivity packaging of very thin, stress-sensitive devices such as TSSOP's. Performance attributes are intended to meet or exceed JEDEC Level 1 for all packages and have no or limited post-mold cure, fast cure cycle times tailored to specific applications and excellent adhesion to Cu and Pd-Ni leadframes.

General Information			
Features	Semi-conductive		
	Low hygroscopicity		
	Laser marking		
	Fast molding cycle		
	Fast curing		
	Good formability		
Uses	Thin wall packaging		
Forms	Liquid		
Processing Method	Resin transfer molding		
Physical	Nominal Value	Unit	Test Method
Specific Gravity	1.98	g/cm <sup>3</sup>	ASTM D792
Mechanical	Nominal Value	Unit	Test Method
Flexural Modulus			ASTM D790
22°C	2.22	MPa	ASTM D790
260°C	0.103	MPa	ASTM D790
Flexural Strength			ASTM D790
22°C	0.0120	MPa	ASTM D790
260°C	0.00108	MPa	ASTM D790
Thermal	Nominal Value	Unit	Test Method
Glass Transition Temperature	146	°C	ASTM E1356
CLTE - Flow	9.8E-6	cm/cm/°C	ASTM D696
Thermal Conductivity	1.0	W/m/K	ASTM C177
Electrical	Nominal Value	Unit	Test Method
Volume Resistivity	1.0E+12	ohms · cm	ASTM D257
Dielectric Strength	55	kV/mm	ASTM D149
Dielectric Constant (1 MHz)	3.80		ASTM D150
Flammability	Nominal Value	Unit	Test Method
Flame Rating (3.18 mm)	V-0		UL 94
Additional Information			

Recommended Storage Temperature: <5°C Life @ 5°C, defined as not more than 40% loss of spiral flow based on original values.: 6 months Life @ 22°C, defined as not more than 40% loss of spiral flow based on original values.: 2 days Life @ 35°C, defined as not more than 40% loss of spiral flow based on original values.: 0.5 days Spiral Flow, 175°C, 1000 psi: 90 cm Shimadzu Viscosity, 175°C, 1000 psi: 43 poise Ram Follower Gel Time, 175°C, 1000 psi: 17 sec Ash Content: 87 % Hydrolyzable Halides: <1 ppm Moisture Absorption, 85°C/85%RH, 168 hrs: 0.23% Cull Hot Hardness, Shore D: 79 Volume Resistivity, 22°C: 1e12 ohm-cm Volume Resistivity, 150°C: 1e9 ohm-cm All test specimens are transfer molded and post cured for 4 hours at 175°C  
Linear Thermal Expansion, Alpha 1: 9.8 cm<sup>-6</sup>/cm/°C  
Linear Thermal Expansion, Alpha 2: 39.3 cm<sup>-6</sup>/cm/°C

#### Injection instructions

Resin Transfer Molding:

Molding Temperature: 170 to 185°C

Molding Pressure: 750 to 1250 psi

In Mold Cure Time: 70 to 120 sec

Post Mold Cure Time, 175°C: 0 to 4 hr

The information and data on this page are provided by manufacturers and document providers. SHANGHAI SUSHENG assumes no legal liability. It is strongly recommended to verify all technical data with material suppliers before final material selection. All rights belong to the original authors. If any infringement occurs, please contact us immediately.

#### Recommended distributors for this material

### Susheng Import & Export Trading Co., Ltd.

Tel: +86 21 5895 8519

Phone: +86 13424755533

Email: sales@su-jiao.com

No. 215, Lianhe North Road, Fengxian District, Shanghai, China



WECHAT